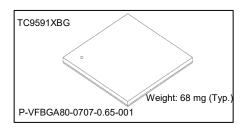
CMOS Digital Integrated Circuit Silicon Monolithic

TC9591XBG

Automotive Peripheral Devices

Overview

The MIPI® CSI-2SM to Parallel port and Parallel port to CSI-2 (TC9591XBG) is a bridge device that has both functions to convert MIPI data transfers from devices such as a camera to an application processor over a Parallel port interface and to convert parallel data transfers to an application over a MIPI CSI-2 interface. All internal registers can be accessed through I²C or SPI (in CSI out case only).



Features

- CSI-2 TX/RX interface
- → MIPI CSI-2 compliant (Version 1.01 Revision 0.04 2 April 2009)
- ♦ Configurable to TX or RX controller
- ♦ Supports up to 1Gbps per data lane
- ♦ Supports up to 4 data lanes
- ♦ Supports video data formats
- RX: RAW8/10/12/14, YUV422 (CCIR/ITU 8/10-bit), RGB888/666/565 and User-Defined 8-bit
- TX: YUV422 (CCIR/ITU 8/10-bit), YUV444, RGB888/666/565 and RAW8/10/12/14
- Parallel Port Interface
- ♦ Supports data formats
- 24-bit bus un-packed format (Both Input and Output mode)
 - RGB888/666/565, RAW8/10/12/14 and YUV422 8-bit (on 8/16-bit data bus) and 10-bit data formats.
- > YUV444 (Parallel Input mode only)
- YUV422 8-bit ITU BT.656 and ITU BT.601 (Parallel input mode only)
 - ➤ Up to 100 MHz PCLK frequency for Output mode, and 166 MHz for Input mode.
- I²C Slave Interface (CS = L)
- ♦ Configure all TC9591XBG internal registers
- SPI Slave Interface (Only applicable in CSIOut configuration, MSEL = H, and CS = H)
 - SPI interface support for up to 25 MHz operation.
 - → Configure all TC9591XBG internal registers

- GPIO signals
- ♦ 3 GPIO signals
 - Three GPIO signals can be configured as control signals (MCLK, CXRST, XShutdown) for CSI-2 RX device.
- Or one GPIO signal can be configured as INT signal for Parallel interface.
- System
- Clock and power management support to achieve low power states.
- Power supply inputs
 - ♦ Core and MIPI D-PHY: 1.2 V
- ♦ I/O: 1.8 V or 3.3 V
- Operation temperature Ta = -40 °C to 105 °C
- AEC-Q100 qualified with the following definition
- → Grade 2 : -40 °C to 105 °C ambient operating temperature range

Rev.1.0



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REFERENCES

- MIPI D-PHY, "MIPI_D-PHY_specification_v01-00-00, May 14, 2009"
 MIPI CSI-2, "MIPI Alliance Standard for Camera Serial Interface 2 (CSI-2) Version 1.01 Revision Nov 2010"
- 3. I²C bus specification, version 2.1, January 2000, Philips Semiconductor

1. Overview

The MIPI CSI-2 to Parallel port and Parallel port to CSI-2 (TC9591XBG) is a bridge device that has both functions to convert MIPI data transfers from devices such as a camera to an application processor over a Parallel port interface and to convert parallel data transfers to an application over a MIPI CSI-2 interface. All internal registers can be accessed through I²C or SPI (in CSI out case only).

There are several system configurations where TC9591XBG is typically used.

- CSI-2 RX with Parallel output mode for scanner application. In this mode, TC9591XBG (CSI-2 to Parallel converter) is a bridge device that converts serial data transfers from devices such as a camera to an application processor over a parallel interface.
- CSI-2 TX with Parallel Input mode for Analog TV, TelePresence Type, and Specialty/Older Cameras application. In this mode, TC9591XBG (Parallel to CSI-2 converter) is a bridge device that converts parallel data transfers to an application over a MIPI CSI-2 interface.

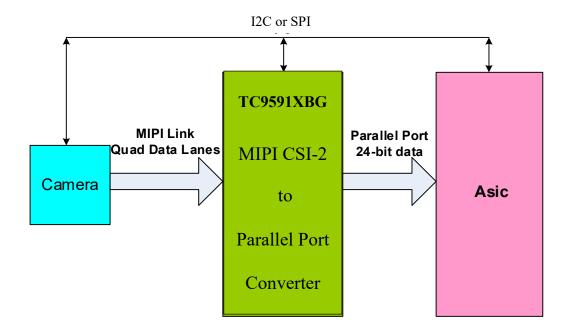


Figure 1.1 System Overview with TC9591XBG in CSI-2 RX to Parallel Port Configuration

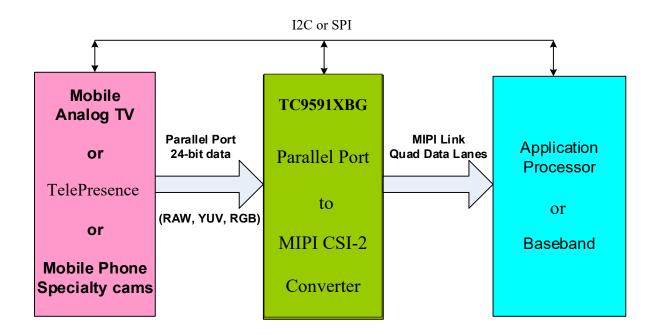


Figure 1.2 System Overview with TC9591XBG in Parallel Port to CSI-2 TX Configuration



2. Features

Below are the main features supported by TC9591XBG.

- CSI-2 TX/RX Interface
 - ♦ MIPI CSI-2 compliant (Version 1.01 Revision 0.04 2 April 2009)
 - ♦ Configurable to TX or RX controller
 - ♦ Supports up to 1Gbps per data lane
 - ♦ Supports up to 4 data lanes
 - Supports video data formats
 - RX: RAW8/10/12/14, YUV422 (CCIR/ITU 8/10-bit), RGB888/666/565 and User-Defined 8-bit
 - TX: YUV422 (CCIR/ITU 8/10-bit), YUV444, RGB888/666/565 and RAW8/10/12/14
- Parallel Port Interface
 - ♦ Supports data formats
 - 24-bit bus un-packed format (Both Input and Output mode)
 - RGB888/666/565, RAW8/10/12/14 and YUV422 8-bit (on 8/16-bit data bus) and 10-bit data formats.
 - > YUV444 (Parallel Input mode only)
 - YUV422 8-bit ITU BT.656 and ITU BT.601 (Parallel input mode only)
 - ♦ Up to 100 MHz PCLK frequency for Output mode, and 166 MHz for Input mode.
- I²C Slave Interface (CS = L)
 - ♦ Support for normal (100 kHz), fast mode (400 kHz) and special mode (1 MHz)
 - ♦ Configure all TC9591XBG internal registers
- SPI Slave Interface (Only applicable in CSIOut configuration, MSEL = H, and CS = H)
 - ♦ SPI interface support for up to 25 MHz operation.
 - ♦ Configure all TC9591XBG internal registers
- GPIO signals
 - ♦ 3 GPIO signals
 - Three GPIO signals can be configured as control signals (MCLK, CXRST, XShutdown) for CSI-2 RX device.
 - Or one GPIO signal can be configured as INT signal for Parallel interface.
- System
 - ♦ Clock and power management support to achieve low power states.
- Power supply inputs
 - ♦ Core and MIPI D-PHY: 1.2 V
 - ♦ I/O: 1.8 V or 3.3 V
- AEC-Q100 Qualified with the following definition
 - ♦ Grade 2: -40 °C to 105 °C ambient operating temperature range



2.1. Typical Power Consumption

Parallel_In → CSI_Out, 500 MHz CSICLk, 1080P @60fps						
	VDDIO (3.3 V) VDDC (1.2 V) VDD_MIPI (1.2 V) Total Power					
Current (mA)	0.44	40.4	24.5			
Power (mW)	1.45	48.48	29.40	79.33		

CSI_In → Parallel_Out, 500 MHz CSICLk, 100 MHz PClk ColorBar @60fps				
VDDIO (3.3 V) VDDC (1.2 V) VDD_MIPI (1.2 V) Total Power				
Current (mA)	18.9	13.9	12.3	
Power (mW)	62.37	16.68	14.76	93.81



3. External Pins

3.1. TC9591XBG pinout description

TC9591XBG resides in BGA pin packages. The following table gives the signals of TC9591XBG and their function.

Table 3.1 TC9591XBG Functional Signal List

			O		Initial	netional digital List	
Group	Pin Name	MSEL=0	MSEL=1	Type	(O)	Function	Note
	RESX	I	I	Sch	-	System reset input, active low	-
	REFCLK	I	I	N	-	Reference clock input (6MHz – 40MHz)	-
	MSEL	I	I	N	-	Mode Select 1'b0: CSI-2 RX in -> Parallel out 1'b1: Parallel in -> CSI-2 TX	-
System: Reset & Clock (4)	CS	I	I	N	-	Chip Select, active low MSEL= 0 (CSI-2 RX in -> Parallel out) - When CS = 0, chip selected Normal operation - When CS = 1, chip not selected Cannot access to internal registers and optionally Parallel output ports can be tri-state when 0x0004[15] is set MSEL= 1 (Parallel in -> CSI-2 TX) - CS = 0, I ² C I/F is selected - CS = 1, SPI I/F is chosen	-
	MIPI_CP	I	0	PHY	LP11	MIPI-CSI clock positive	-
	MIPI_CN	I	0	PHY	LP11	MIPI-CSI clock negative	-
	MIPI_D0P	I	0	PHY	LP11	MIPI-CSI Data 0 positive	-
	MIPI D0N	ı	0	PHY	LP11	MIPI-CSI Data 0 negative	-
MIPI-CSI	MIPI D1P	I	0	PHY	LP11	MIPI-CSI Data 1 positive	-
(10)	MIPI D1N	1	0	PHY	LP11	MIPI-CSI Data 1 negative	_
	MIPI D2P	i	0	PHY	LP11	MIPI-CSI Data 2 positive	_
	MIPI D2N	i	0	PHY	LP11	MIPI-CSI Data 2 negative	-
	MIPI D3P	I	0	PHY	LP11	MIPI-CSI Data 3 positive	-
	MIPI_D3N	I	0	PHY	LP11	MIPI-CSI Data 3 negative	-
I2C I/F	I2C_SCL	I		Sch	-	I ² C serial clock or SPI_SCLK	4 mA
(2)	I2C_SDA		I	Sch	-	I ² C serial data or SPI_MOSI	4 mA
Parallel	PD[23:0]	0	I	N	L	Parallel Port Data - PD[23:12] can configs to be GPIO[15:4]	4 mA
Port I/F	VVALID	0	1	N	L	Parallel port VVALID signal	4 mA
(27)	HVALID	0	I	N	L	Parallel port HVALID signal	4 mA
	PCLK	0	I	N	L	Parallel Port Clock signal	4 mA
GPIO (3)	GPIO[2:0]	ı	1	N	-	GPIO[2:0] signals CSI-2 RX in -> Parallel out - (GPIO[0] option to become MCLK signal) - (GPIO[1] option to become CXRST or INT) - (GPIO[2] option to become XShutdown) Parallel in -> CSI-2 TX - (GPIO[0] option to become MCLK signal) - (GPIO[1] option to become SPI_SS or INT) - (GPIO[2] option to become SPI_MISO)	4 mA
	VDDC (1.2 V)	NA	-	-	-	VDD for Internal Core (2)	-
POWER	VDDIO (1.8 V or 3.3 V)	NA	-	-	-	VDDIO is for IO power supply (3)	-
(9)	VDD_MIPI (1.2 V)	NA	-	-	-	VDD for the MIPI CSI2 (2)	-
Ground (25)	VSS	NA	-	_	_	Ground	-



3.2. TC9591XBG BGA80 Pin Count Summary

Table 3.2 TC9591XBG BGA 80 Pin Count Summary

Group Name	Pin Count	Notes
SYSTEM	4	-
MIPI-CSI	10	-
I2C I/F	2	-
GPIO	3	-
Parallel Port I/F	27	-
POWER	9	IO, MIPI and Core Power
GROUND	25	-
TOTAL	80	



3.3. TC9591XBG Pin Layout

A1	A2	А3	A4	A5	A6	A7	A8	A9	A10
VSS	PD17	PD19	PD21	PD23	GPIO2	VDDC	I2C_SCL	MSEL	VSS
B1	B2	В3	В4	B 5	В6	В7	B 8	В9	B10
VDDC	PD16	PD18	PD20	PD22	GPIO1	VSS	I2C_SDA	RESX	VDDIO
C1	C2	C3	C4	C 5	C6	C7	C8	C9	C10
PD15	PD14							MIPI_D3P	MIPI_D3N
D1	D2	D3	D4	D5	D6	D7	D8	D9	D10
PD13	PD12		VSS	VSS	VSS	VSS		MIPI_D2P	MIPI_D2N
E1	E2	E3	E4	E 5	E6	E7	E8	E9	E10
PD11	PD10		VSS	VSS	VSS	VSS		VSS	VDD_MIPI
F1	F2	F3	F4	F5	F6	F7	F8	F9	F10
	• 4	ГЭ		ГЭ	го	F/	го	ГЭ	FIU
PD9	PD8	13	VSS	VSS	VSS	VSS	го	MIPI_CP	MIPI_CN
		G3					G8		
PD9	PD8		VSS	VSS	VSS	VSS		MIPI_CP	MIPI_CN G10
PD9 G1	PD8 G2		VSS G4	VSS G5	VSS G6	VSS G7		MIPI_CP G9	MIPI_CN G10
PD9 G1 PD7	PD8 G2 PD6	G 3	VSS G4 VSS	VSS G5 VSS	VSS G6 VSS	VSS G7 VSS	G8	MIPI_CP G9 MIPI_D1P	MIPI_CN G10 MIPI_D1N
PD9 G1 PD7 H1	PD8 G2 PD6 H2	G 3	VSS G4 VSS	VSS G5 VSS	VSS G6 VSS	VSS G7 VSS	G8	MIPI_CP G9 MIPI_D1P H9	MIPI_CN G10 MIPI_D1N H10
PD9 G1 PD7 H1 VDDIO	PD8 G2 PD6 H2 VSS	G3 H3	VSS G4 VSS H4	VSS G5 VSS H5	VSS G6 VSS H6	VSS G7 VSS H7	G8 H8	MIPI_CP G9 MIPI_D1P H9 VSS	MIPI_CN G10 MIPI_D1N H10 VDD_MIPI J10
PD9 G1 PD7 H1 VDDIO J1	PD8 G2 PD6 H2 VSS J2	G3 H3	VSS G4 VSS H4	VSS G5 VSS H5	VSS G6 VSS H6	VSS G7 VSS H7	G8 H8 J8	MIPI_CP G9 MIPI_D1P H9 VSS J9	MIPI_CN G10 MIPI_D1N H10 VDD_MIPI J10

Figure 3.1 TC9591XBG 80-Pin Layout (Top View)

4. Package

4.1. TC9591XBG Package

The packages for TC9591XBG are described in the figures below.

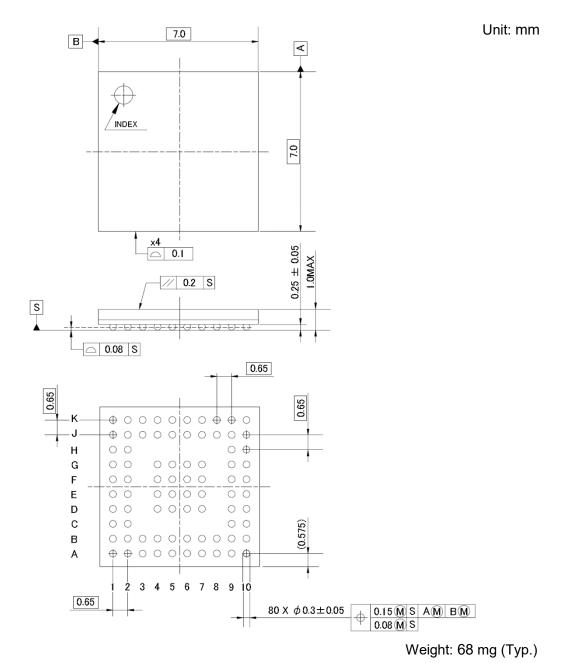


Figure 4.1 TC9591XBG P-VFBGA80-0707-0.65-001 package

Table 4.1 TC9591XBG P-VFBGA80-0707-0.65-001 Mechanical Dimension

Dimension	Min	Тур.	Max
Solder ball pitch	-	0.65 mm	-
Solder ball height	0.20 mm	0.25 mm	0.30 mm
Package dimension	-	7.0 × 7.0 mm ²	-
Package height	-	-	1.0 mm

5. Electrical Characteristics

5.1. Absolute Maximum Ratings

VSS= 0V reference

Parameter	Symbol	Rating	Unit
Supply voltage (1.8V - Digital IO)	VDDIO	-0.3 to +3.9	V
Supply voltage (1.2V – Digital Core)	VDDC	-0.3 to +1.8	V
Supply voltage (1.2V – MIPI CSI PHY)	VDD_MIPI	-0.3 to +1.8	V
Input voltage (CSI IO)	V _{IN_CSI}	-0.3 to VDD_MIPI+0.3	V
Output voltage (CSI IO)	V _{OUT_CSI}	-0.3 to VDD_MIPI+0.3	V
Input voltage (Digital IO)	$V_{IN_{IO}}$	-0.3 to VDDIO+0.3	V
Output voltage (Digital IO)	V _{OUT_IO}	-0.3 to VDDIO+0.3	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-40 to +125	°C

5.2. Operating Condition

VSS= 0V reference

Parameter	Symbol	Min	Тур.	Max	Unit
Supply voltage (1.8V – Digital IO)	VDDIO	1.65	1.8	1.95	V
Supply voltage (3.3V – Digital IO)	VDDIO	3.0	3.3	3.6	V
Supply voltage (1.2V – Digital Core)	VDDC	1.1	1.2	1.3	V
Supply voltage (1.2V – MIPI CSI PHY)	VDD_MIPI	1.1	1.2	1.3	٧
Operating temperature (ambient temperature with voltage applied)	Та	-40	+25	+105	°C
Supply Noise Voltage	V_{SN}	-	-	100	mV_{pp}



5.3. DC Electrical Specification

Parameter	Symbol	Min	Тур.	Max	Unit
Input voltage, High level input Note1	V _{IH}	0.7 VDDIO	-	VDDIO	V
Input voltage, Low level input Note1	V_{IL}	0	-	0.3 VDDIO	V
Input voltage High level CMOS Schmitt Trigger Note1, Note2	V _{IHS}	0.7 VDDIO	-	VDDIO	V
Input voltage Low level CMOS Schmitt Trigger	V_{ILS}	0	-	0.3 VDDIO	V
Output voltage High level Note1, Note2 (Condition: IOH = -0.4mA)	V _{OH}	0.8 VDDIO	-	VDDIO	V
Output voltage Low level	V _{OL}	0	-	0.2 VDDIO	V
(Condition: IOL = 2mA) Input leak current, High level (Normal IO or Pull-up IO) (Condition: VIN = +VDDIO, VDDIO = 3.6V)	I _{ILH1} (Note4)	-10	-	10	μΑ
Input leak current, High level (Pull-down IO) (Condition: VIN = +VDDIO, VDDIO = 3.6V)	I _{ILH2} (Note4)	-	-	100	μА
Input leak current, Low level (Normal IO or Pull-down IO) (Condition: VIN = 0V, VDDIO = 3.6V)	I _{ILL1} (Note5)	-10	-	10	μA
Input leak current, Low level (Pull-up IO) (Condition: VIN = 0V, VDDIO = 3.6V)	I _{ILL2} (Note5)	-	-	200	μΑ

Note1: Each power source is operating within operation condition.

Current output value is specified to each IO buffer individually. Output voltage changes with output Note2:

current value.

Normal pin or Pull-up IO pin applied VDDIO supply voltage to Vin (input voltage) Note4:

Note5: Normal pin or Pull-down IO pin applied VSSIO (0V) to Vin (input voltage)



6. Revision History

Table 6.1 Revision History

Revision	Date	Description
1.0	2020-06-05	Newly released



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